© Copyrig	l Composition D ht 2005. IPC, Bannocl al and Pan-American	burn, Illinois. A	Il rights reserved untions.	under both	This docume level parts, t	ent is a declarat he declaration e	ion of the su	bstances v s all lower	within the manufactur level materials for w	er listed iter hich the ma	n. Note: if nufacturer	the item is an as has engineering	sembly with low responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Ty _I http://www.ipc.org/IPC-175x Distribute				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mfg Information			
Supplier Information														
Company name* Com			Company unique ID			Unique ID Authority				Response Date*				
nsemi									2024-05-04					
Contact Name Title -			Fitle - Contact			Phone - Contact*				Email - Contact*				
Product-Env-Stewards Produ			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - F			e - Representative			Phone - Representative*			Email - Representative*					
Product-Env-Stewards Product			duct Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Requester Item Number	Requester Item Number Mfr Item		n Number Mfr Item Name			Effective Date	Version	M	Ianufacturing Site	W	eight*	UOM	Unit Type	
	DF01S	DF01S2 BR		BR SDIP PN 2A 100V		2024-05-04		P.	PANJITFG		0.0	mg	Each	
Anufacturing Proccess I	nformation													
Terminal Plating / Grid	Terminal Plating / Grid Array Material Terminal Ba		Alloy J-STD-020 MSL Rating		L Rating	Peak Process Body Temperatur		are Max Time at Peak Tempera		e Numb	er of Reflow Cyc	cles		
Matte Tin (Sn) - annealed Cl		CU Alloy	y <u>1</u>			260 C		С	30 seco		seconds 3			
omments														
vel 1 - maximum time at peak t	emperature during s	oldering is 10-3	0 seconds											
or more information regarding	material composition	please refer to	page 3											

RoHS Material Composition Declar	ation			Declaration Type *	Detailed
Directive 2015/863/EU amending Rol Directive 2011/65/EU	(Pb), Mercury (Hg), Hexav		ninated Biphenyls (PBB), Polybror	dmium and quantity limit of 0.1% by mass (100 ninated Diphenyl Ethers (PBDE), and Bis(2-eth	
cadmium, hexavalentchromium, polyb contains a RoHS restricted substance i encompass all such components.Suppl as of the date that Supplier completes Company acknowledges that Supplier independently verified information pro- certification in this paragraph.If the Co	rominated biphenyls and/or polybror nexcess of an applicable quantity lim ier certifies that it gathered the inforr this form.Supplier acknowledges that may have relied on informationprovi ovided by others, Supplier agrees that ompany and the Supplier enter into a clusivesource of the Supplier's liabili	ninated diphenyl ethers (each a "R it, please indicate below which, if nation it provides in this form usin Company will rely on this certifud ded by others in completing this f , at a minimum, itssuppliers have written agreement with respect to ty and the Company's remedies for	toHS restricted substance") in exce any, RoHS exemption you believe ag appropriate methods to ensure it cation in determining the complian orm, and that Supplier may not hav provided certifications regarding th the identified part,the terms and co or issues that arise regarding inform	ropean Union member states) of the part identifies so of the applicable quantity limit identified about may apply. If the part is an assembly with lows a accuracy and that such information is true and ce of its products with European Union member re independently verified such information. How heir contributions to the part, and those certifica motions of that agreement, including any warra nation the Supplier provides in this form. In the	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the inty rights and/or remedies provided as part of
RoHS Declaration * 4	- Item(s) does not contain RoHS restr	icted substances per the definition	above except for selected exempti	ons Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high meltin Exemption: 7c-I Electrical and elect	g temperature type solders (i.e. lead ronic components containing lead i	l based solder alloys containing n a glass or ceramic other than	85% by weight or more lead). dielectric ceramic in capacitors, o	e.g. piezoelectronic devices, or in a glass or ce	eramic matrix compound.
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the rec Requester) and click on Submit For			Supplier Acceptance drop-down	. This will display the signature area. Digital	ly sign the declaration (if required by the
Supplier Digital Signature	Rastislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	3.6	mg	Supplier	Silicon (Si)	7440-21-3		3.3768	mg
			В	Nickel (Ni)	7440-02-0		0.0324	mg
			Supplier	Gold (Au)	7440-57-5		0.018	mg
			А	Lead Oxide (PbO)	1317-36-8	7c	0.1728	mg
Die Attach Solder	2.595	mg	Supplier	Silver (Ag)	7440-22-4		0.0649	mg
			А	Lead (Pb)	7439-92-1	7a	2.4004	mg
			Supplier	Tin (Sn)	7440-31-5		0.1297	mg
Lead Frame	63.63	mg	Supplier	Iron (Fe)	7439-89-6		0.0764	mg
			Supplier	Copper (Cu)	7440-50-8		63.5346	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0191	mg
Mold Compound-Black	233.175	mg		Metal Hydroxide	proprietary data		8.1611	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		18.654	mg
			Supplier	Carbon Black (C)	1333-86-4		1.1659	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		186.54	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		18.654	mg
Plating	7.0	mg	Supplier	Tin (Sn)	7440-31-5		7	mg